

## 1. General description

Planar passivated four quadrant triac in a SOT428 (DPAK) surface-mountable plastic package intended for use in general purpose bidirectional switching and phase control applications.

## 2. Features and benefits

- High blocking voltage capability
- Less sensitive gate for improved noise immunity
- Planar passivated for voltage ruggedness and reliability
- Surface mountable package
- Triggering in all four quadrants

## 3. Applications

- General purpose motor control
- General purpose switching

## 4. Quick reference data

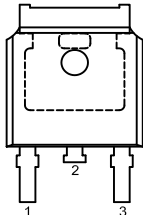

Table 1. Quick reference data

| Symbol                        | Parameter                            | Conditions  | Min | Typ | Max | Unit |
|-------------------------------|--------------------------------------|---|-----|-----|-----|------|
| $V_{\text{DRM}}$              | repetitive peak off-state voltage    |   | -   | -   | 800 | V    |
| $I_{\text{T(RMS)}}$           | RMS on-state current                 | full sine wave; $T_{\text{mb}} \leq 107\text{ °C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>         | -   | -   | 4   | A    |
| $I_{\text{TSM}}$              | non-repetitive peak on-state current | full sine wave; $T_{\text{j(init)}} = 25\text{ °C}$ ; $t_{\text{p}} = 20\text{ ms}$ ; <a href="#">Fig. 4</a> ; <a href="#">Fig. 5</a> | -   | -   | 25  | A    |
|                               |                                      | full sine wave; $T_{\text{j(init)}} = 25\text{ °C}$ ; $t_{\text{p}} = 16.7\text{ ms}$   | -   | -   | 27  | A    |
| $T_{\text{j}}$                | junction temperature                 |   | -   | -   | 125 | °C   |
| <b>Static characteristics</b> |                                      |   |     |     |     |      |
| $I_{\text{GT}}$               | gate trigger current                 | $V_{\text{D}} = 12\text{ V}$ ; $I_{\text{T}} = 0.1\text{ A}$ ; T2+ G+; $T_{\text{j}} = 25\text{ °C}$ ; <a href="#">Fig. 7</a>         | -   | 5   | 35  | mA   |
|                               |                                      | $V_{\text{D}} = 12\text{ V}$ ; $I_{\text{T}} = 0.1\text{ A}$ ; T2+ G-; $T_{\text{j}} = 25\text{ °C}$ ; <a href="#">Fig. 7</a>         | -   | 8   | 35  | mA   |
|                               |                                      | $V_{\text{D}} = 12\text{ V}$ ; $I_{\text{T}} = 0.1\text{ A}$ ; T2- G-; $T_{\text{j}} = 25\text{ °C}$ ; <a href="#">Fig. 7</a>         | -   | 11  | 35  | mA   |
|                               |                                      | $V_{\text{D}} = 12\text{ V}$ ; $I_{\text{T}} = 0.1\text{ A}$ ; T2- G+; $T_{\text{j}} = 25\text{ °C}$ ; <a href="#">Fig. 7</a>         | -   | 30  | 70  | mA   |

| Symbol                  | Parameter                             | Conditions  |  | Min | Typ | Max | Unit |
|-------------------------|---------------------------------------|---|--|-----|-----|-----|------|
| I <sub>H</sub>          | holding current                       | V <sub>D</sub> = 12 V; T <sub>j</sub> = 25 °C; <a href="#">Fig. 9</a>   |  | -   | 5   | 15  | mA   |
| V <sub>T</sub>          | on-state voltage                      | I <sub>T</sub> = 5 A; T <sub>j</sub> = 25 °C; <a href="#">Fig. 10</a>   |  | -   | 1.4 | 1.7 | V    |
| Dynamic characteristics |                                       |   |  |     |     |     |      |
| dV <sub>D</sub> /dt     | rate of rise of off-state voltage     | V <sub>DM</sub> = 536 V; T <sub>j</sub> = 125 °C; (V <sub>DM</sub> = 67% of V <sub>DRM</sub> ); exponential waveform; gate open circuit |  | 100 | 250 | -   | V/μs |
| dV <sub>com</sub> /dt   | rate of change of commutating voltage | V <sub>D</sub> = 400 V; T <sub>j</sub> = 95 °C; dI <sub>com</sub> /dt = 1.8 A/ms; I <sub>T</sub> = 4 A; gate open circuit               |  | -   | 50  | -   | V/μs |

5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description                    | Simplified outline  | Graphic symbol  |
|-----|--------|--------------------------------|---|---|
| 1   | T1     | main terminal 1                | <br>DPAK (SOT428) | <br>sym051 |
| 2   | T2     | main terminal 2                |   |   |
| 3   | G      | gate                           |   |   |
| mb  | T2     | mounting base; main terminal 2 |   |   |

6. Ordering information

Table 3. Ordering information

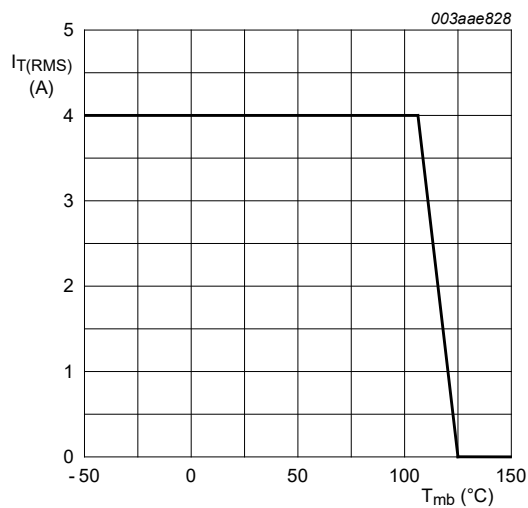
| Type number | Package |   |         |
|-------------|---------|---|---------|
|             | Name    | Description   | Version |
| BT136S-800  | DPAK    | plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped) | SOT428  |

## 7. Limiting values

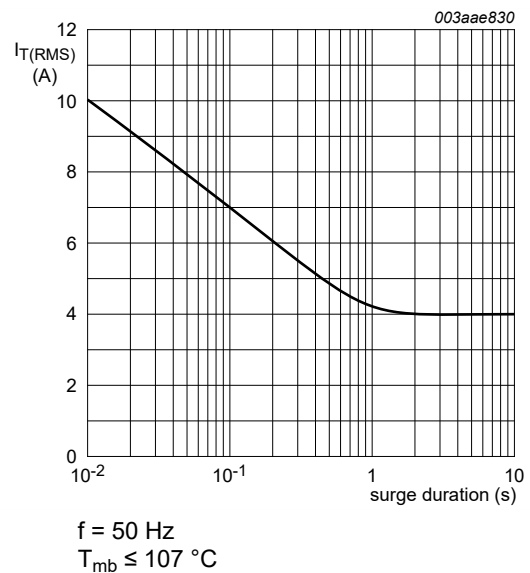
**Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

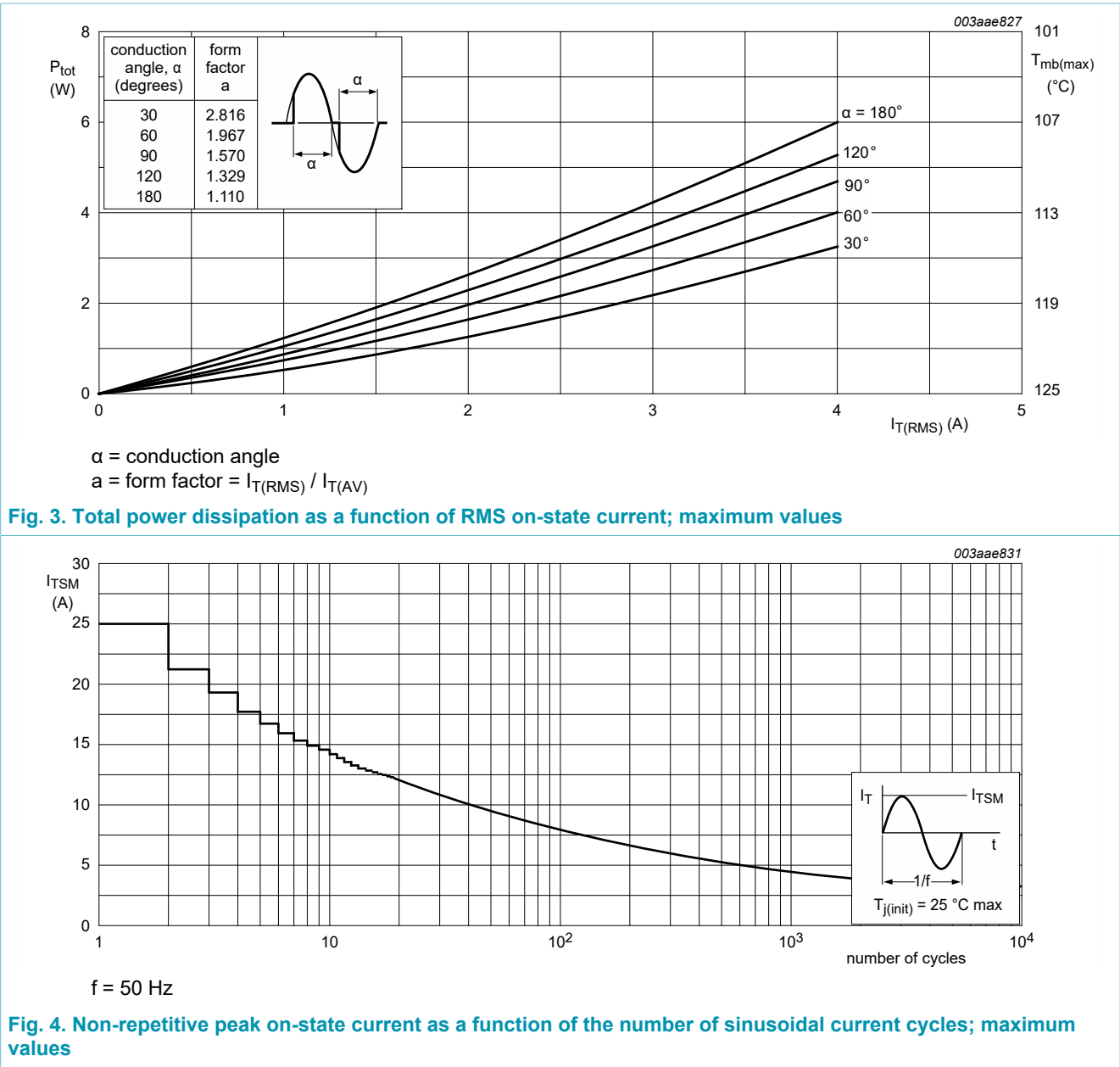
| Symbol              | Parameter                            | Conditions  | Min | Max | Unit                   |
|---------------------|--------------------------------------|---|-----|-----|------------------------|
| $V_{\text{DRM}}$    | repetitive peak off-state voltage    |   | -   | 800 | V                      |
| $I_{\text{T(RMS)}}$ | RMS on-state current                 | full sine wave; $T_{\text{mb}} \leq 107\text{ °C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>         | -   | 4   | A                      |
| $I_{\text{TSM}}$    | non-repetitive peak on-state current | full sine wave; $T_{\text{j(init)}} = 25\text{ °C}$ ; $t_{\text{p}} = 20\text{ ms}$ ; <a href="#">Fig. 4</a> ; <a href="#">Fig. 5</a> | -   | 25  | A                      |
|                     |                                      | full sine wave; $T_{\text{j(init)}} = 25\text{ °C}$ ; $t_{\text{p}} = 16.7\text{ ms}$   | -   | 27  | A                      |
| $I^2t$              | $I^2t$ for fusing                    | $t_{\text{p}} = 10\text{ ms}$ ; SIN   | -   | 3.1 | $\text{A}^2\text{s}$   |
| $di_{\text{T}}/dt$  | rate of rise of on-state current     | $I_{\text{G}} = 150\text{ mA}$  | -   | 50  | $\text{A}/\mu\text{s}$ |
| $I_{\text{GM}}$     | peak gate current                    |   | -   | 2   | A                      |
| $P_{\text{GM}}$     | peak gate power                      |   | -   | 5   | W                      |
| $P_{\text{G(AV)}}$  | average gate power                   | over any 20 ms period   | -   | 0.5 | W                      |
| $T_{\text{stg}}$    | storage temperature                  |   | -40 | 150 | °C                     |
| $T_{\text{j}}$      | junction temperature                 |   | -   | 125 | °C                     |

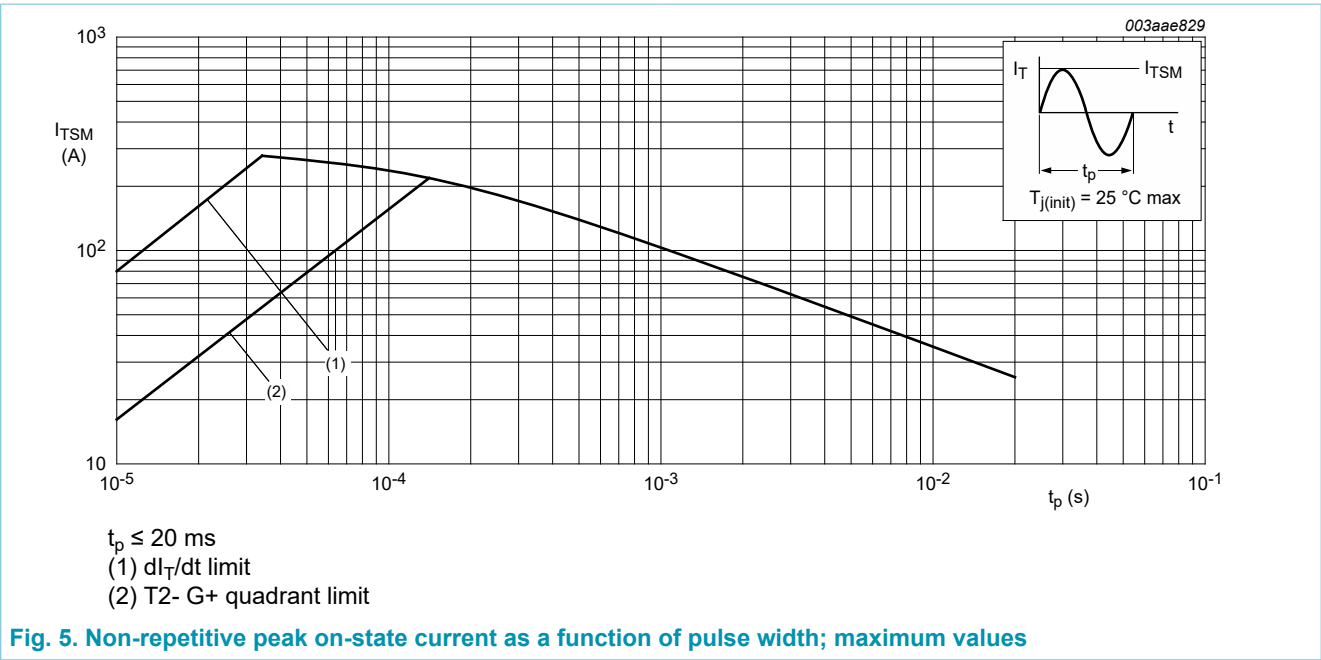


**Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values**



**Fig. 2. RMS on-state current as a function of surge duration; maximum values**





8. Thermal characteristics

Table 5. Thermal characteristics

| Symbol         | Parameter  | Conditions  |  | Min | Typ | Max | Unit |
|----------------|--|---|--|-----|-----|-----|------|
| $R_{th(j-mb)}$ | thermal resistance from junction to mounting base    | half cycle; Fig. 6  |  | -   | -   | 3.7 | K/W  |
|                |  | full cycle; Fig. 6  |  | -   | -   | 3   | K/W  |
| $R_{th(j-a)}$  | thermal resistance from junction to ambient free air | in free air; printed circuit board (FR4) mounted; standard footprint, single-sided copper, tin-plated |  | -   | 75  | -   | K/W  |

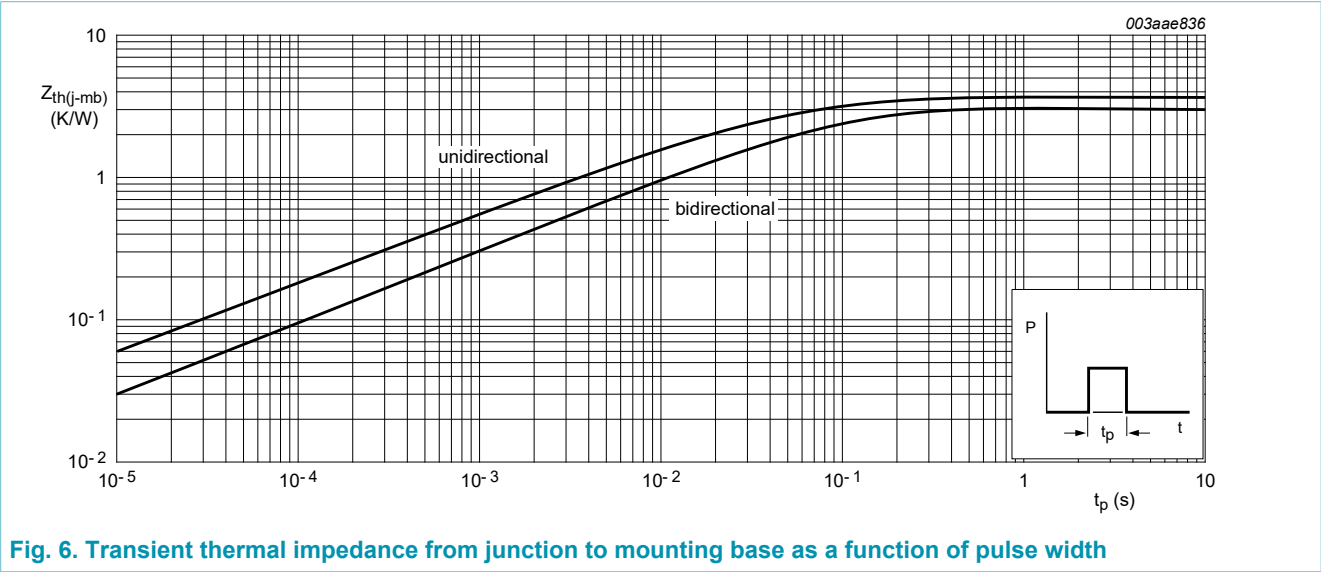
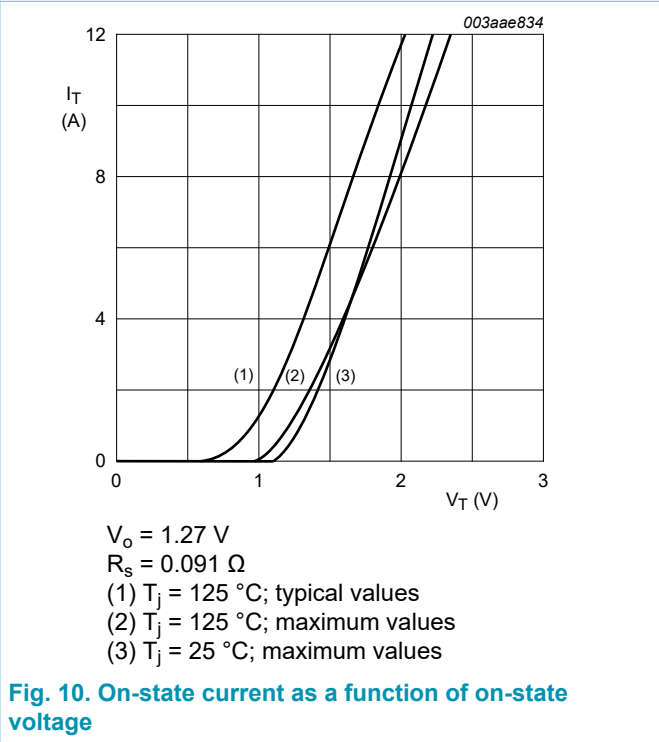
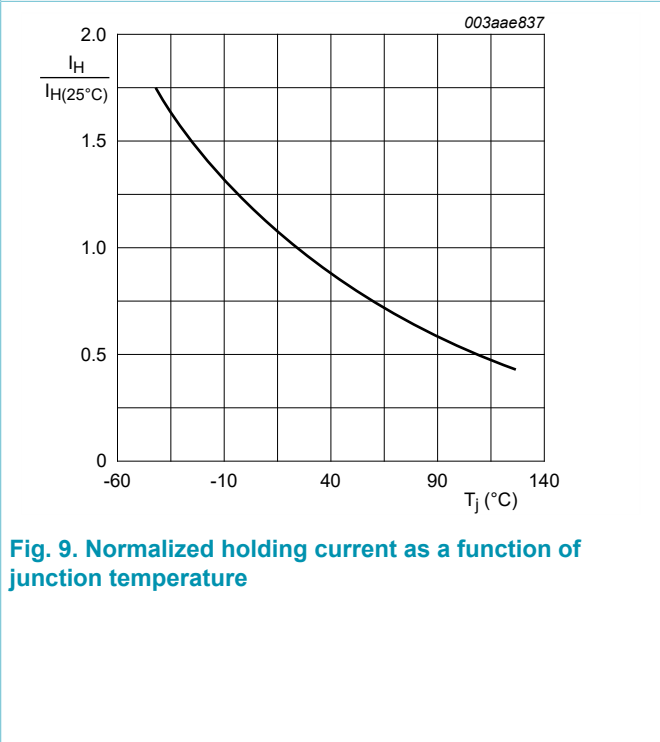
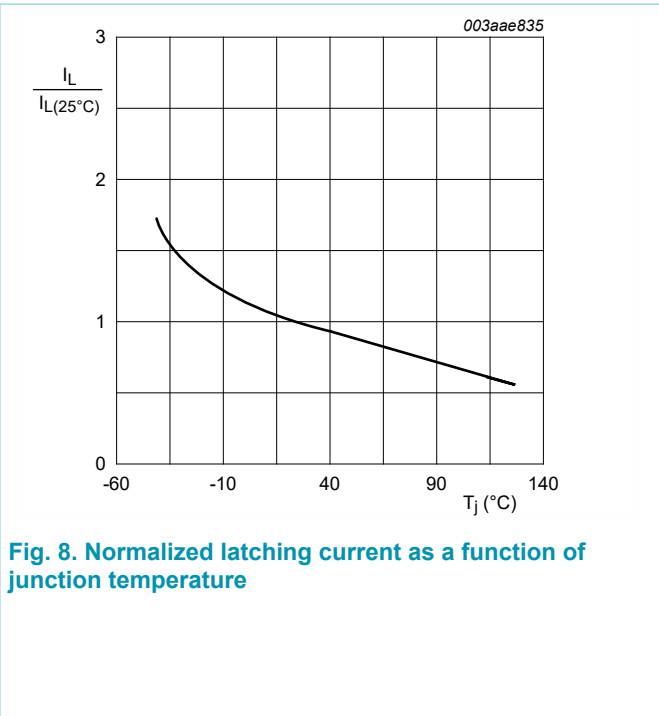
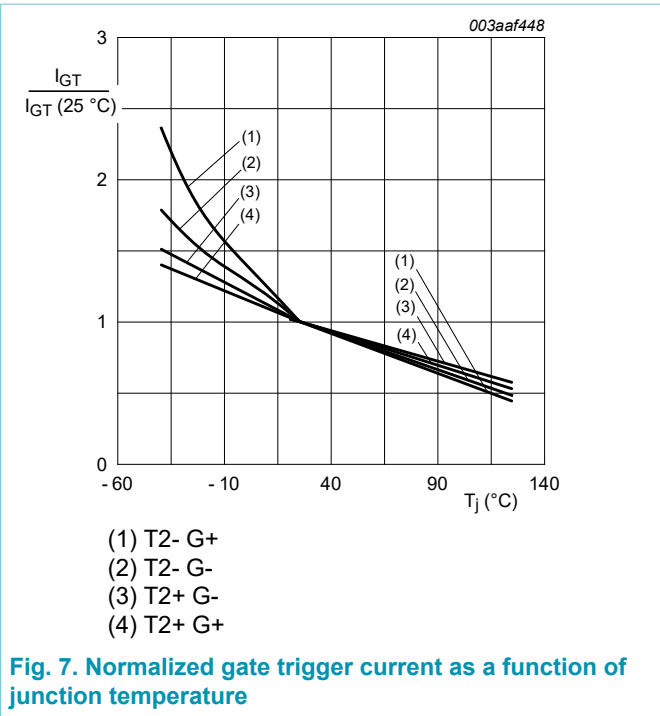


Fig. 6. Transient thermal impedance from junction to mounting base as a function of pulse width

## 9. Characteristics

Table 6. Characteristics

| Symbol                         | Parameter                             | Conditions  |  | Min  | Typ | Max | Unit             |
|--------------------------------|---------------------------------------|---|--|------|-----|-----|------------------|
| <b>Static characteristics</b>  |                                       |   |  |      |     |     |                  |
| $I_{GT}$                       | gate trigger current                  | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2+ G+;<br>$T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 7</a>                       |  | -    | 5   | 35  | mA               |
|                                |                                       | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2+ G-;<br>$T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 7</a>                       |  | -    | 8   | 35  | mA               |
|                                |                                       | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2- G-;<br>$T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 7</a>                       |  | -    | 11  | 35  | mA               |
|                                |                                       | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2- G+;<br>$T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 7</a>                       |  | -    | 30  | 70  | mA               |
| $I_L$                          | latching current                      | $V_D = 12\text{ V}$ ; $I_G = 0.1\text{ A}$ ; T2+ G+;<br>$T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 8</a>                       |  | -    | 7   | 20  | mA               |
|                                |                                       | $V_D = 12\text{ V}$ ; $I_G = 0.1\text{ A}$ ; T2+ G-;<br>$T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 8</a>                       |  | -    | 16  | 30  | mA               |
|                                |                                       | $V_D = 12\text{ V}$ ; $I_G = 0.1\text{ A}$ ; T2- G-;<br>$T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 8</a>                       |  | -    | 5   | 20  | mA               |
|                                |                                       | $V_D = 12\text{ V}$ ; $I_G = 0.1\text{ A}$ ; T2- G+;<br>$T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 8</a>                       |  | -    | 7   | 30  | mA               |
| $I_H$                          | holding current                       | $V_D = 12\text{ V}$ ; $T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 9</a>   |  | -    | 5   | 15  | mA               |
| $V_T$                          | on-state voltage                      | $I_T = 5\text{ A}$ ; $T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 10</a>   |  | -    | 1.4 | 1.7 | V                |
| $V_{GT}$                       | gate trigger voltage                  | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; $T_j = 25\text{ }^\circ\text{C}$ ;<br><a href="#">Fig. 11</a>                              |  | -    | 0.7 | 1   | V                |
|                                |                                       | $V_D = 400\text{ V}$ ; $I_T = 0.1\text{ A}$ ; $T_j = 125\text{ }^\circ\text{C}$ ;<br><a href="#">Fig. 11</a>                            |  | 0.25 | 0.4 | -   | V                |
| $I_D$                          | off-state current                     | $V_D = 800\text{ V}$ ; $T_j = 125\text{ }^\circ\text{C}$  |  | -    | 0.1 | 0.5 | mA               |
| <b>Dynamic characteristics</b> |                                       |   |  |      |     |     |                  |
| $dV_D/dt$                      | rate of rise of off-state voltage     | $V_{DM} = 536\text{ V}$ ; $T_j = 125\text{ }^\circ\text{C}$ ; ( $V_{DM} = 67\%$ of $V_{DRM}$ ); exponential waveform; gate open circuit |  | 100  | 250 | -   | V/ $\mu\text{s}$ |
| $dV_{com}/dt$                  | rate of change of commutating voltage | $V_D = 400\text{ V}$ ; $T_j = 95\text{ }^\circ\text{C}$ ; $dI_{com}/dt = 1.8\text{ A/ms}$ ; $I_T = 4\text{ A}$ ; gate open circuit      |  | -    | 50  | -   | V/ $\mu\text{s}$ |





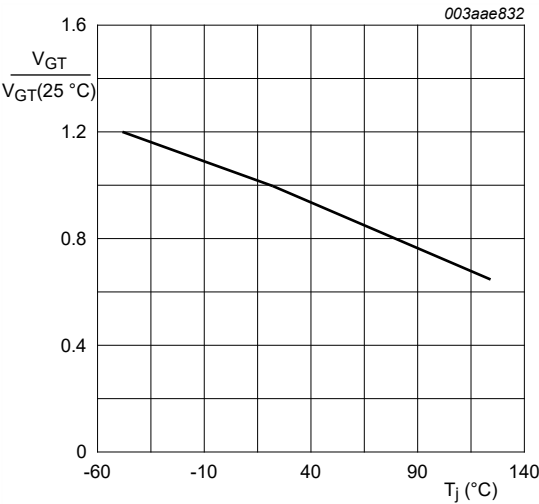
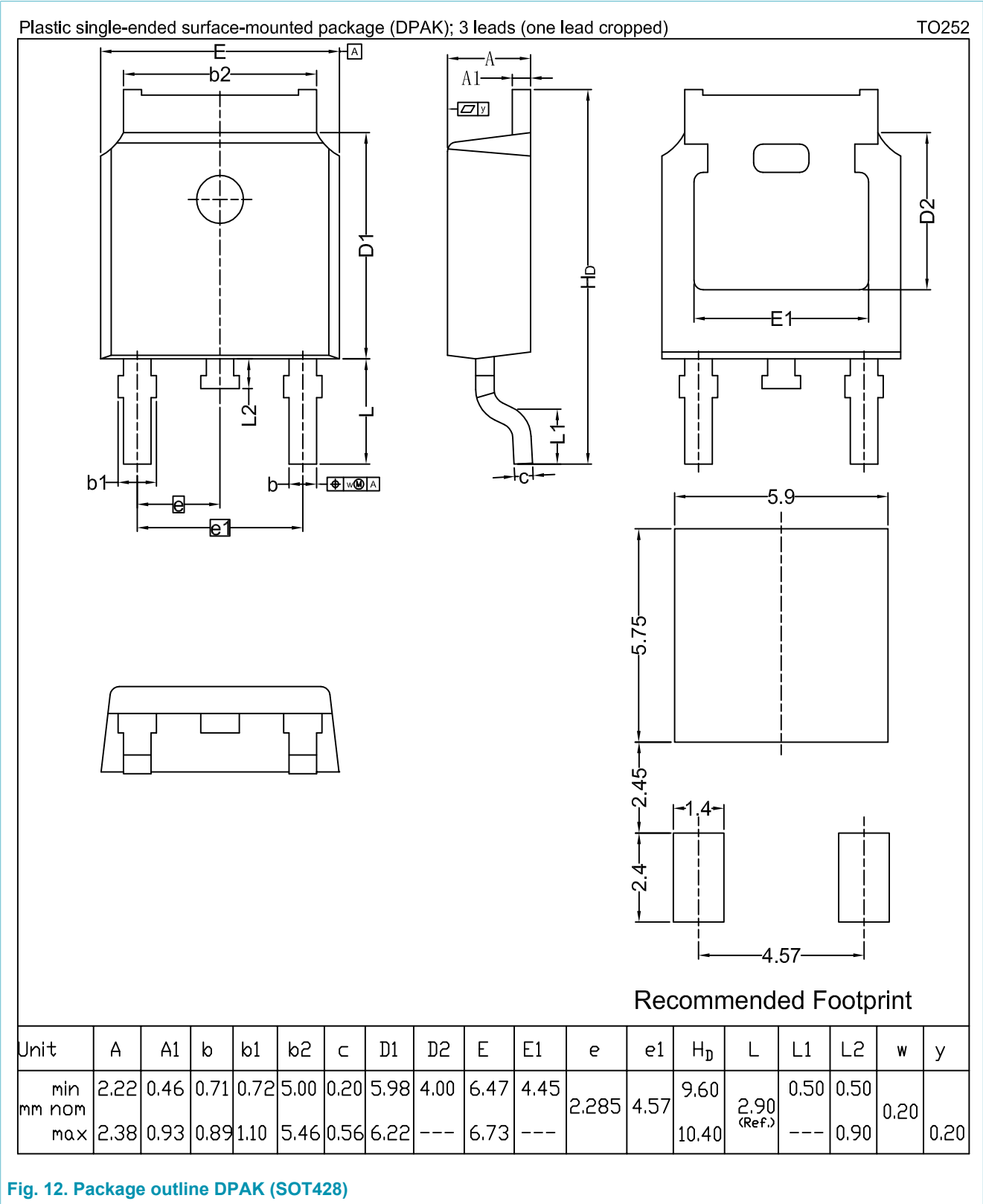


Fig. 11. Normalized gate trigger voltage as a function of junction temperature

10. Package outline



## 11. Legal information

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| Document status [1][2]         | Product status [3] | Definition  |
|--------------------------------|--------------------|---|
| Objective [short] data sheet   | Development        | This document contains data from the objective specification for product development. |
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- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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Date of release: 6 July 2018



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